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FGH40T65UPD

650 V, 40 A 场截止沟道 IGBT

特性

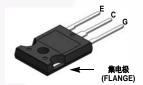
- 最大结温: T_J = 175°C
- 正温度系数,易于并联运行
- 高电流能力
- 低饱和电压: V_{CE(sat)} = 1.65 V (Typ.) @ I_C = 40 A
- 器件 100% 经过 I_{LM(2) 测试}
- 高输入阻抗
- 紧密的参数分布
- 符合 RoHS 标准
- 短路耐用性 > 5 μs @25°C

概述

飞兆半导体的新型场截止沟道 IGBT 系列产品采用创新型场截止 沟道 IGBT 技术,为光伏逆变器、 UPS、焊机和数码发电机等低 导通和开关损耗至关重要的应用提供了最佳性能。

应用

- 光伏逆变器、 UPS、焊机、数码发电机
- 通信电源、ESS





绝对最大额定值

符号	说明		额定值	单位
V _{CES}	集电极一发射极间电压		650	V
V _{GES}	栅极一发射极间电压		± 20	V
*GES	瞬态栅极一发射极间电压		± 25	V
I _C	集电极电流	@ T _C = 25°C	80	A
10	集电极电流	$@ T_C = 100^{\circ}C$	40	A
I _{CM (1)}	集电极脉冲电流		120	A
I _{LM (2)}	箝位感性负载电流	@ T _C = 25°C	120	A
I _F	二极管正向电流	@ T _C = 25°C	40	A
	二极管正向电流	@ T _C = 100°C	20	A
I _{FM(1)}	二极管最大正向脉冲电流		120	A
P_{D}	最大功耗	@ T _C = 25°C	268	W
	最大功耗	@ T _C = 100°C	134	W
SCWT	短路耐受时间	@ T _C = 25°C	5	μs
T _J	工作结温		-55 至 +175	°C
T _{stg}	存储温度范围		-55 至 +175	°C
T _L	用于焊接的最大引脚温度,距离外壳	5 1/8",持续 5 秒	300	°C

注意:

1: 重复额定值: 脉宽受最大结温限制

2: Ic = 120 A, Vce = 400 V, Rg = 15 Ω

热性能

符号	参数	典型值	最大值	单位
$R_{\theta JC}(IGBT)$	结点一壳体的热阻		0.56	°C/W
$R_{\theta JC}(Diode)$	结点一壳体的热阻		1.71	°C/W
$R_{\theta JA}$	结至环境热阻		40	°C/W

封装标识与定购信息

器件编号	顶标	封装	包装方法	卷尺寸	带宽	数量
FGH40T65UPD	FGH40T65UPD	TO-247 A03	塑料管	不适用	不适用	30

IGBT 电气特性 T_C = 25°C 除非另有说明

符号	参数	测试条件	最小值	典型值	最大值	单位
关断特性						
BV _{CES}	集电极一发射极击穿电压	$V_{GE} = 0 \text{ V}, I_{C} = 1 \text{ mA}$	650			V
$\frac{\Delta BV_{CES}}{\Delta T_{J}}$	击穿温度系数电压	$V_{GE} = 0 \text{ V}, I_{C} = 250 \mu\text{A}$		0.65		V/°C
I _{CES}	集电极切断电流	V _{CE} = V _{CES} , V _{GE} = 0 V			250	μA
I _{GES}	G-E 漏电流	V _{GE} = V _{GES} , V _{CE} = 0 V			±400	nA
导通特性						
V _{GE(th)}	G-E 阈值电压	$I_C = 40 \text{ mA}, V_{CE} = V_{GE}$	4.0	6.0	7.5	V
		I _C = 40 A, V _{GE} = 15 V		1.65	2.3	V
V _{CE(sat)}	集电极一发射极间饱和电压	$I_C = 40 \text{ A}, V_{GE} = 15 \text{ V},$ $T_C = 175^{\circ}\text{C}$		2.1		V
动态特性						
C _{ies}	输入电容			2730	3630	pF
C _{oes}	输出电容	$V_{CE} = 30 \text{ V}, V_{GE} = 0 \text{ V},$ f = 1 MHz		82	110	pF
C _{res}	反向传输电容	1 = 1 WITZ		48	72	pF
开关特性						
t _{d(on)}	导通延迟时间			20	26	ns
t _r	上升时间			26	34	ns
t _{d(off)}	关断延迟时间	$V_{CC} = 400 \text{ V}, I_{C} = 40 \text{ A},$		144	187	ns
t _f	下降时间	$R_G = 7 \text{ W, } V_{GE} = 15 \text{ V,}$ 感性负载, $T_C = 25 ^{\circ} \text{C}$		17	22	ns
E _{on}	导通开关损耗			1.59	2.1	mJ
E _{off}	关断开关损耗			0.58	0.76	mJ
E _{ts}	总开关损耗			2.17	2.86	mJ
t _{d(on)}	导通延迟时间			19		ns
t _r	上升时间			38		ns
t _{d(off)}	关断延迟时间	$V_{CC} = 400 \text{ V}, I_{C} = 40 \text{ A},$		153		ns
t _f	下降时间	$R_G = 7 \Omega$, $V_{GE} = 15 V$,		60		ns
E _{on}	导通开关损耗	───── 感性负载, T _C = 175 [°] C		1.84		mJ
E _{off}	关断开关损耗			0.98		mJ
E _{ts}	总开关损耗			2.82		mJ
T _{SC}	短路耐受时间	V_{GE} = 15 V, V_{CC} =400 V, R_G = 10 Ω	5			μs
Qg	总栅极电荷	.,		177	265	nC
Q _{ge}	栅极一发射极间电荷	V _{CE} = 400 V, I _C = 40 A, V _{GE} = 15 V		23	35	nC
Q _{gc}	栅极一集电极间电荷	▼GE = 13 V		100	150	nC

二极管电气特性 Tc = 25°C 除非另有说明

符号	参数	测试条件		最小值	典型值	最大值	单位
V _{FM}	二极管正向电压	I _F = 20 A	$T_C = 25^{\circ}C$		2.1	2.7	V
			$T_C = 175^{\circ}C$		1.9		
E _{rec}	反向恢复电能		$T_C = 175^{\circ}C$		96		μJ
t	t _{rr} 二极管反向恢复时间	$II_{c} = 20 \text{ A} \text{ dIc/dI} = 200 \text{ A/ms}$	$T_C = 25^{\circ}C$		33	43	ns
11			$T_C = 175^{\circ}C$		128		
Q _{rr}	二极管反向恢复电荷		$T_C = 25^{\circ}C$		53	74	nC
			$T_C = 175^{\circ}C$		341		

图 1. 典型输出特性

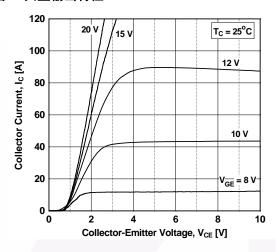


图 2. 典型输出特性

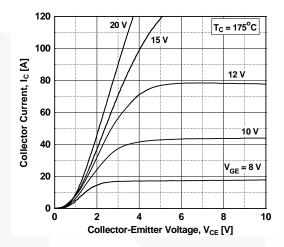


图 3. 饱和电压特性

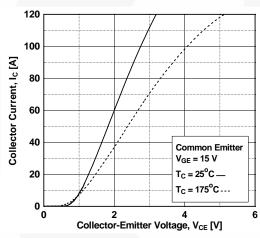


图 4. 饱和电压与可变电流强度下壳温的关系

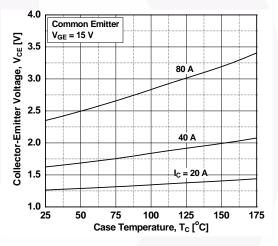


图 5. 饱和电压与 V_{GE} 的关系

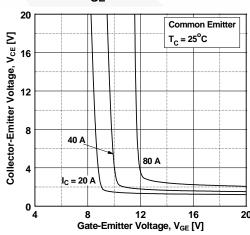


图 6. 饱和电压与 V_{GE} 的关系

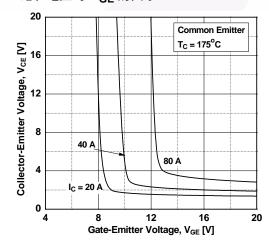


图 7. 电容特性

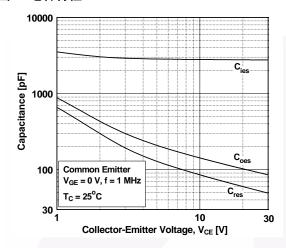


图 8. 栅极电荷特性

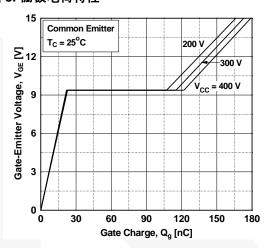


图 9. 导通特性与栅极电阻的关系

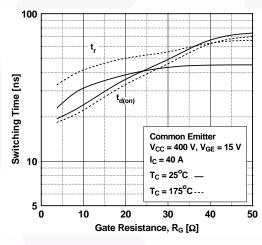


图 10. 关断特性与栅极电阻的关系

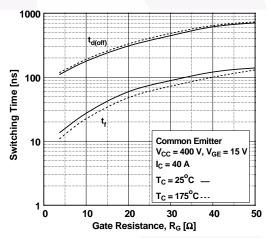


图 11. 开关损耗与栅极电阻的关系

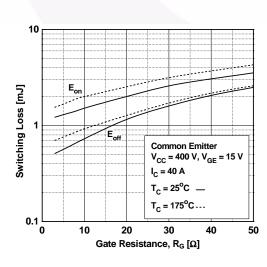


图 12. 导通特性与集电极电流的关系

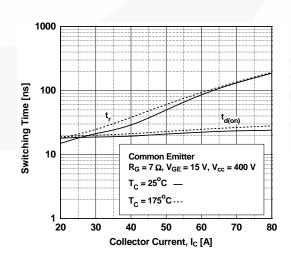


图 13. 关断特性与集电极电流的关系

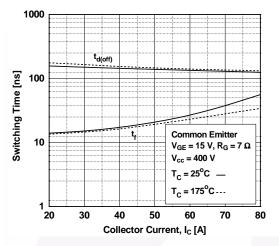


图 14. 开关损耗与集电极电流的关系

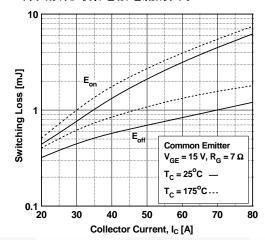


图 15. 负载电流与频率的关系

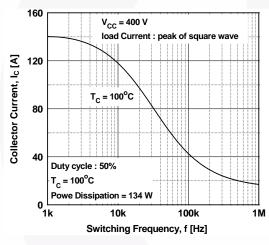


图 16. SOA 特性

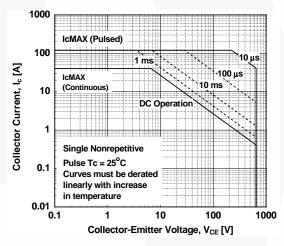


图 17. 正向特性

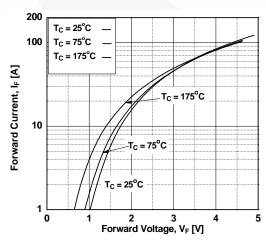


图 18. 反向恢复电流

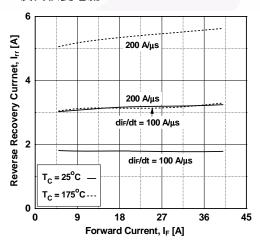


图 19. 反向恢复时间

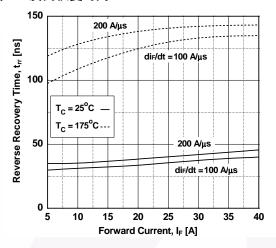


图 20. 存储电荷

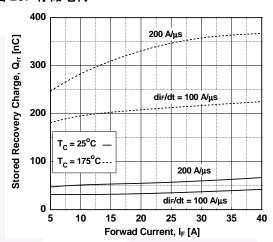


图 21. IGBT 瞬态热阻抗

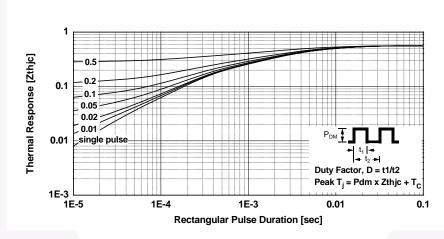
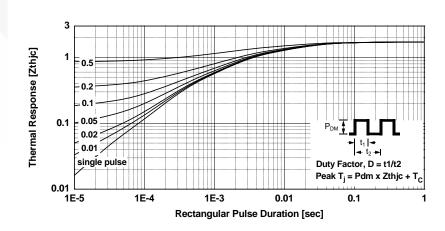
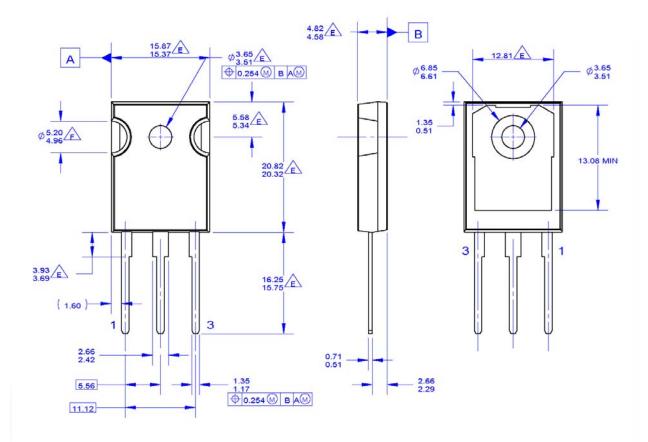


图 22. 二极管瞬态热阻抗



机械尺寸



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- E DOES NOT COMPLY JEDEC STANDARD VALUE
- NOTCH MAY BE SQUARE
- G. DRAWING FILENAME: MKT-TO247A03_REV03

图 23. TO-247, MOLDED, 3 LEAD, JEDEC VARIATION AB (有效)

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